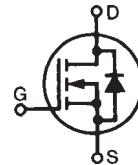


PolarHT™ Power MOSFET

N-Channel Enhancement Mode
Avalanche Rated

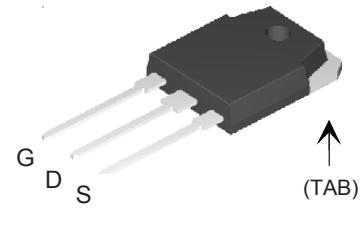
IXTQ 200N06P

V_{DSS} = 60 V
I_{D25} = 200 A
R_{DS(on)} ≤ 6.0 mΩ



Symbol	Test Conditions	Maximum Ratings	
V _{DSS}	T _J = 25°C to 175°C	60	V
V _{DGR}	T _J = 25°C to 175°C; R _{GS} = 1 MΩ	60	V
V _{GS}	Transient	±30	V
V _{GSM}	Continuous	±20	V
I _{D25}	T _C = 25°C	200	A
I _{D(RMS)}	External lead current limit	75	A
I _{DM}	T _C = 25°C, pulse width limited by T _{JM}	400	A
I _{AR}	T _C = 25°C	60	A
E _{AR}	T _C = 25°C	80	mJ
E _{AS}	T _C = 25°C	4.0	J
dv/dt	I _S ≤ I _{DM} , di/dt ≤ 100 A/μs, V _{DD} ≤ V _{DSS} , T _J ≤ 150°C, R _G = 4 Ω	10	V/ns
P _D	T _C = 25°C	714	W
T _J		-55 ... +175	°C
T _{JM}		175	°C
T _{stg}		-55 ... +150	°C
T _L	1.6 mm (0.062 in.) from case for 10 s	300	°C
T _{SOLD}	Plastic body for 10 s	260	°C
M _d	Mounting torque (TO-3P)	1.13/10	Nm/lb.in.
Weight	TO-3P	5.5	g

TO-3P (IXTQ)



G = Gate
S = Source

D = Drain
TAB = Drain

Features

- International standard package
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
 - easy to drive and to protect

Advantages

- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions (T _J = 25°C, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
BV _{DSS}	V _{GS} = 0 V, I _D = 250 μA	60		V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2.5		V
I _{GSS}	V _{GS} = ±20 V _{DC} , V _{DS} = 0		±100	nA
I _{DSS}	V _{DS} = V _{DSS} V _{GS} = 0 V	T _J = 150°C	25 250	μA
R _{DS(on)}	V _{GS} = 10 V, I _D = 60 A V _{GS} = 15 V, I _D = 400 A Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %	5.0	6.0 mΩ	mΩ

Symbol	Test Conditions	Characteristic Values			
		($T_J = 25^\circ C$, unless otherwise specified)	Min.	Typ.	Max.
g_{fs}	$V_{DS} = 10 V; I_D = 60 A$, pulse test	45	65	S	
C_{iss} C_{oss} C_{rss}	$V_{GS} = 0 V, V_{DS} = 25 V, f = 1 \text{ MHz}$	5400		pF	
		3550		pF	
		1360		pF	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	$V_{GS} = 10 V, V_{DS} = 0.5 V_{DSS}, I_D = 60 A$ $R_G = 3.3 \Omega$ (External)	35		ns	
		60		ns	
		90		ns	
		40		ns	
$Q_{g(on)}$ Q_{gs} Q_{gd}	$V_{GS} = 10 V, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$	200		nC	
		37		nC	
		110		nC	
R_{thJC}				0.21	$^\circ C/W$
R_{thCS}			0.21		$^\circ C/W$

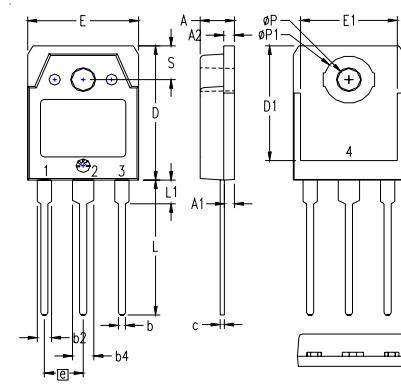
Source-Drain Diode

Characteristic Values

 $(T_J = 25^\circ C$, unless otherwise specified)

Symbol	Test Conditions	Min.	Typ.	Max.
I_s	$V_{GS} = 0 V$		200	A
I_{sm}	Repetitive		400	A
V_{SD}	$I_F = I_s, V_{GS} = 0 V$, Pulse test, $t \leq 300 \mu s$, duty cycle $d \leq 2 \%$		1.5	V
t_{rr} Q_{RM}	$I_F = 25 A, -di/dt = 100 A/\mu s$ $V_R = 30 V, V_{GS} = 0 V$	90		ns
		1.0		μC

TO-3P (IXTQ) Outline



1 - GATE
2 - DRAIN (COLLECTOR)
3 - SOURCE (EMITTER)
4 - DRAIN (COLLECTOR)

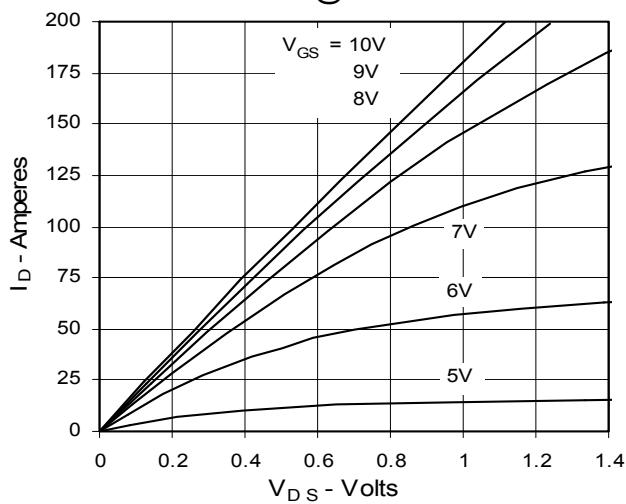
SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.185	.193	4.70	4.90
A1	.051	.059	1.30	1.50
A2	.057	.065	1.45	1.65
b	.035	.045	0.90	1.15
b2	.075	.087	1.90	2.20
b4	.114	.126	2.90	3.20
c	.022	.031	0.55	0.80
D	.780	.791	19.80	20.10
D1	.665	.677	16.90	17.20
E	.610	.622	15.50	15.80
E1	.531	.539	13.50	13.70
e	.215 BSC		5.45 BSC	
L	.779	.795	19.80	20.20
L1	.134	.142	3.40	3.60
ØP	.126	.134	3.20	3.40
ØP1	.272	.280	6.90	7.10
S	.193	.201	4.90	5.10

All metal areas are tin plated.

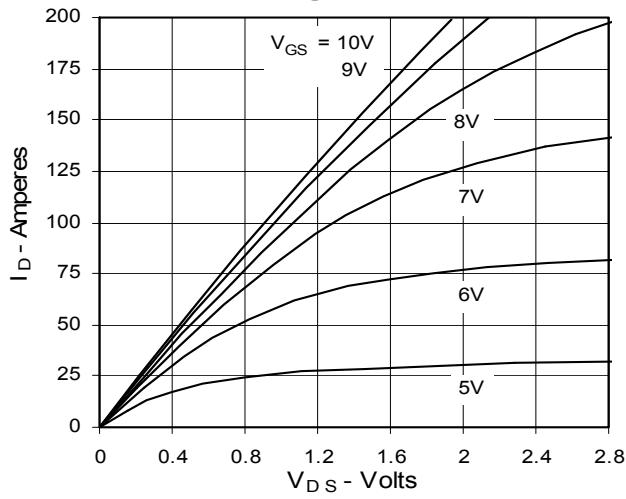
IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 one or more of the following U.S. patents: 4,850,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2

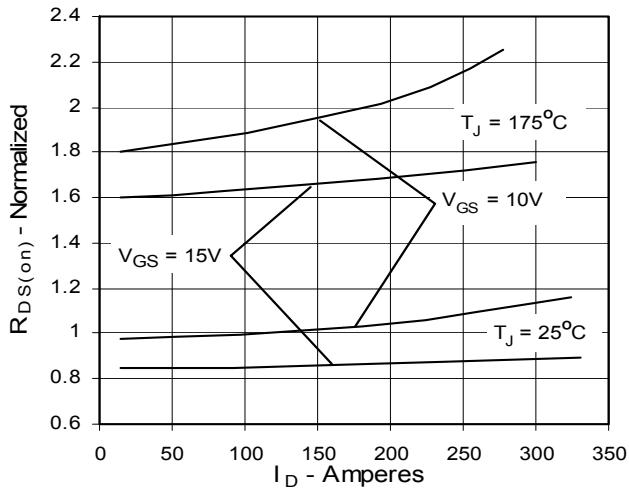
**Fig. 1. Output Characteristics
@ 25°C**



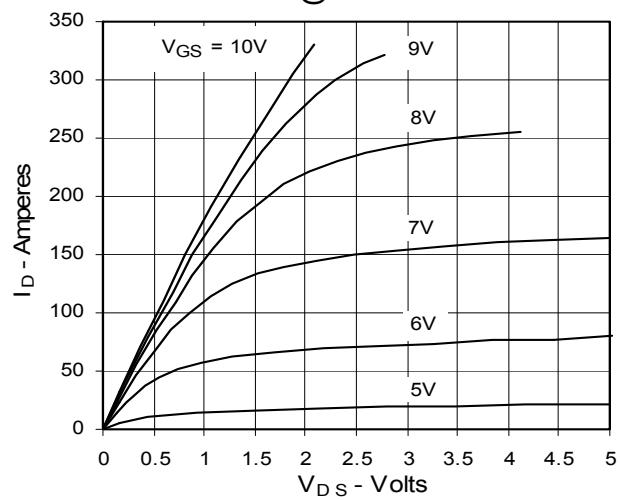
**Fig. 3. Output Characteristics
@ 150°C**



**Fig. 5. $R_{DS(on)}$ Normalized to 0.5 I_{D25}
Value vs. Drain Current**



**Fig. 2. Extended Output Characteristics
@ 25°C**



**Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25}
Value vs. Junction Temperature**

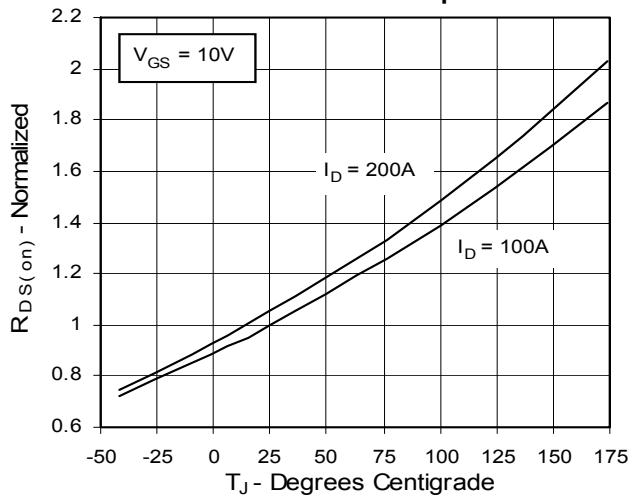


Fig. 6. Drain Current vs. Case Temperature

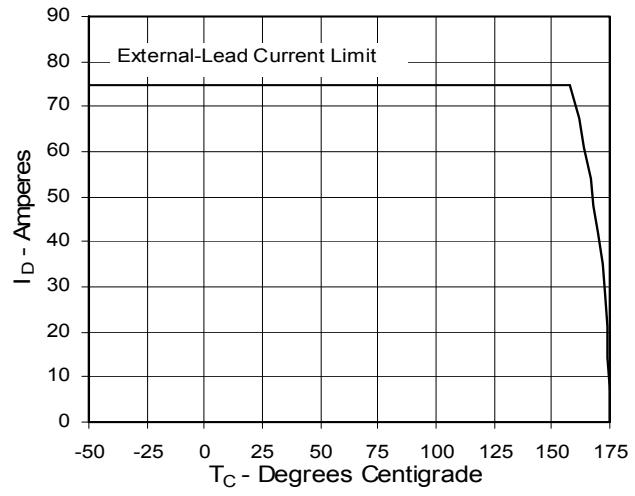
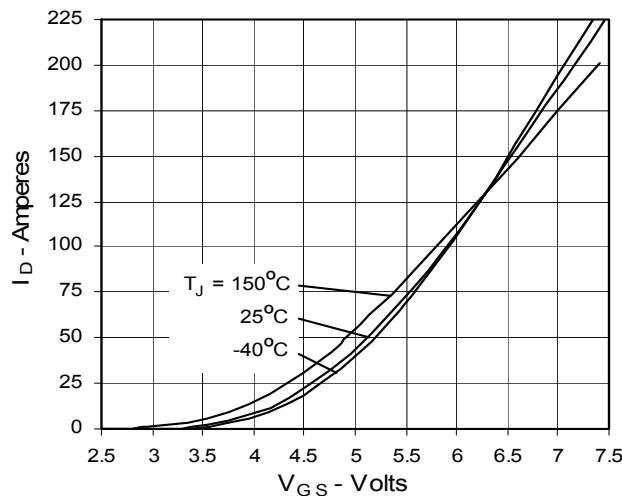
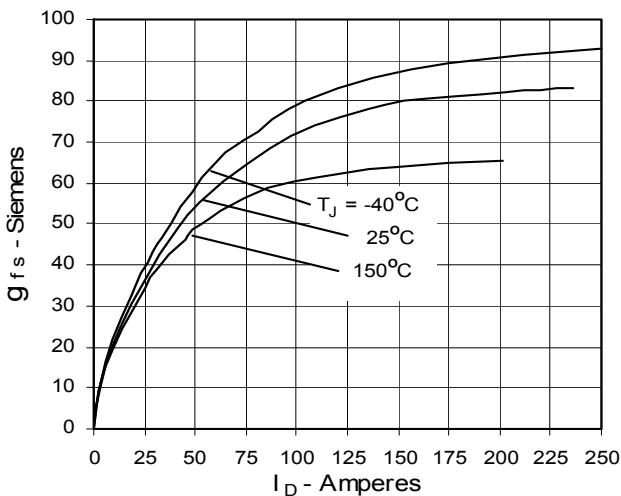
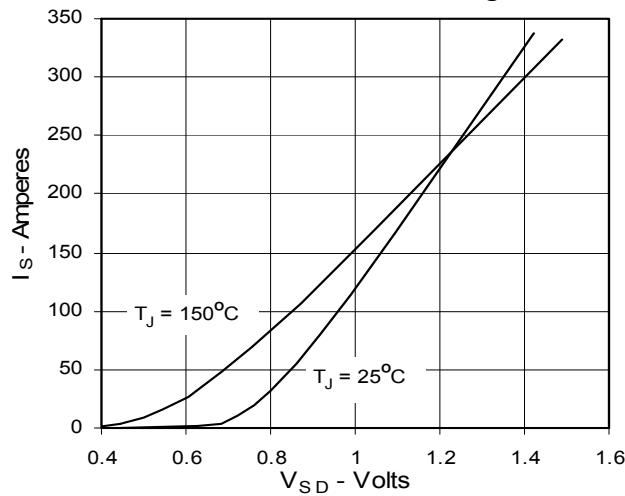
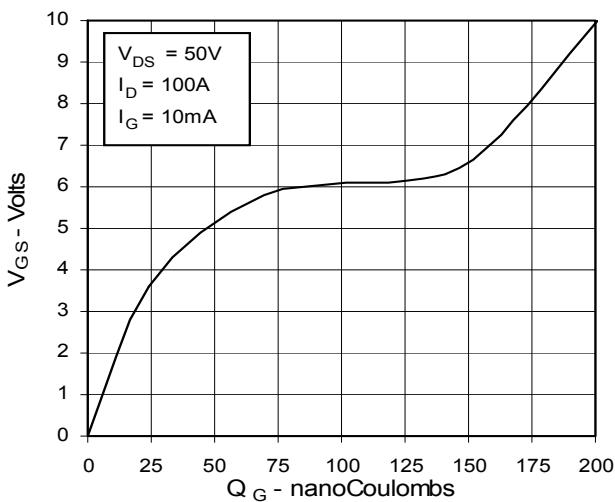
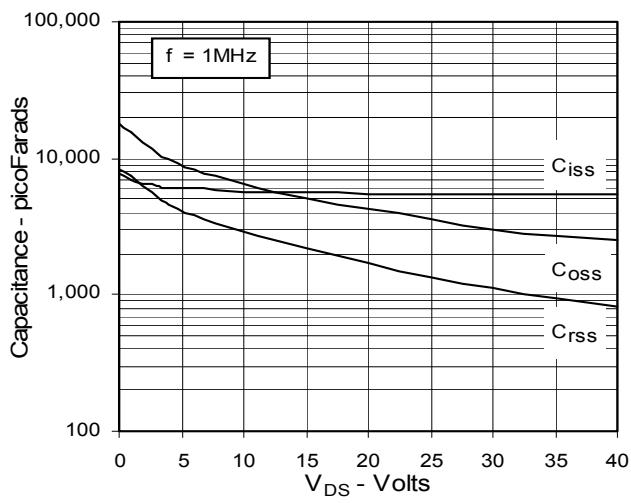
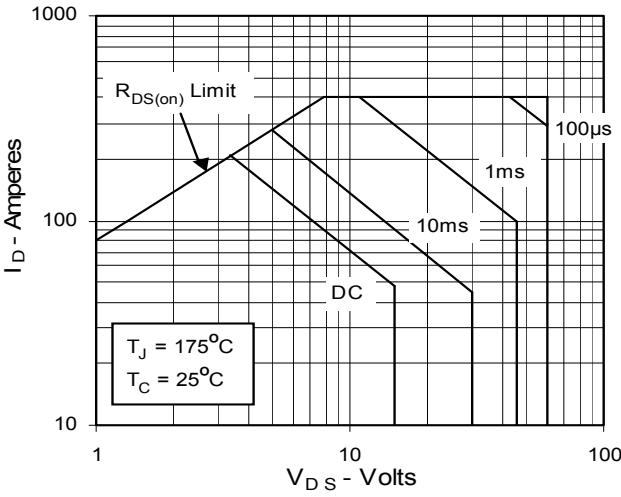


Fig. 7. Input Admittance**Fig. 8. Transconductance****Fig. 9. Source Current vs. Source-To-Drain Voltage****Fig. 10. Gate Charge****Fig. 11. Capacitance****Fig. 12. Forward-Bias Safe Operating Area**

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Fig. 13. Maximum Transient Thermal Resistance